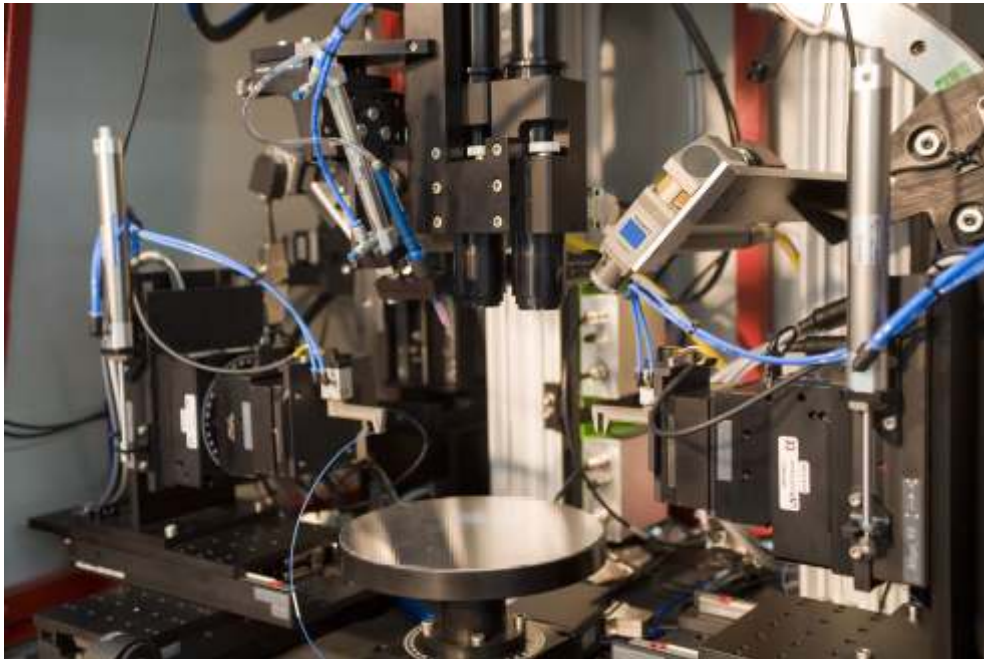


## NanoTest Combo SiP

### Characterization and Packaging for Si Photonics Devices

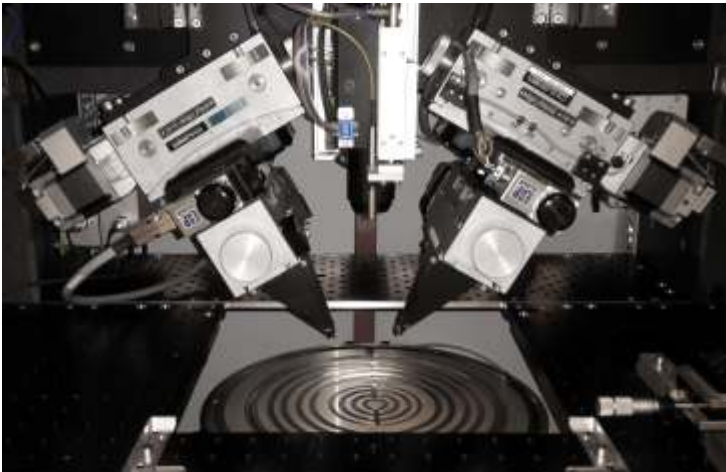


Especially designed for the requirements of Silicon Photonics devices, the NanoTest Combo SiP is ideal for the optical and electrical characterization of structures on up to 12" wafer diameter. Electrical probes are manually positioned and the wafer is moved underneath the probes from device to device. The optional wafer chuck is temperature controlled between 20° C and 100° C.

Two 6-axes alignment stacks position the optical probes with an active alignment and 100 nm repeatability. Machine vision cameras both in the visible and as an option in the near infrared range are used to perform the pre-alignment. The subsequent active alignment with a feedback signal guarantees optimal coupling efficiency.

If packaging capability is required, the central chuck is replaced with a versatile mounting interface. Resin dispensation and UV curing, laser welding and/or laser soldering capability will be added. The alignment stacks precisely position optical components such as fibers, fiber arrays, lenses, lens arrays, detectors and lasers.

- **Suitable for 8" or 12" wafers**
- **20 nm resolution/100 nm repeatability for optical probing**
- **0.3  $\mu\text{m}$  resolution/1  $\mu\text{m}$  repeatability for electrical probing**
- **Heated Chuck Option**
- **Optional Packaging Capability**



When testing is the main application, the wafer will be shuttled in XYZ and Yaw. Electrical probing will be manually adjusted to a fixed device geometry and from there the testing can run automated from device to device.

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